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SPECIFICATIONS

SD12864-FTRE-12-W

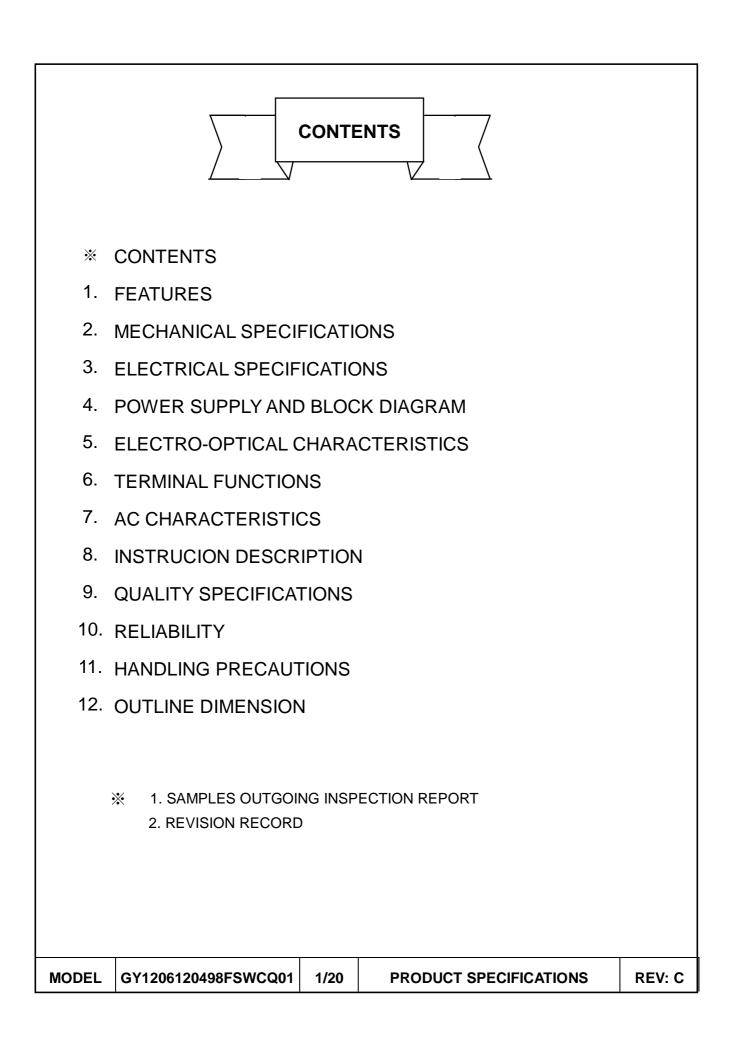
Swissdis 108553

LCD Module Graphic 128x64 Dots With LED Backlight white

Version August 2013

REVISION RECORD (MODEL NO.: GY1206120498FSWCQ01)

Revision	Revision Date	Page	Contents
A B C	2013/05/15 2013/08/15 2014/02/24		Initial Release and Issue Full Specification. Change the Backlight. Change the Outline(Add Data Code).



1. FEATURES

The features of LCD are as follows

* Display mode	: FSTN, Positive, Transflective
* Color	: Display dot : Black
	Background: White
* Display Format	: 128 X 64 Dots
* IC	: Ultra Chip: UC1601x GAD
* Interface Input Data	: Serial and parallel Interface MPU
* Driving Method	: 1/65 Duty, 1/9 Bias
* Viewing Direction	: 12 O'clock
* Backlight	: LED(White)

* LCM technological conditions: RoHS

2. MECHANICAL SPECIFICATIONS

ltem	Specification	Unit
Module Size	79.2(W) x 140.25(H) x 5.5MAX(T)	mm
Viewing Area	70.7MIN(W) x 38.8MIN(H)	mm
Effective Display Area	66.54(W) x 33.26(H)	mm
Character Font	128 x 64 Dots	-
Dot Size	0.50(W) X 0.50(H)	mm
Dot Pitch	0.52(W) X 0.52(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1. Absolute Maximum Ratings (Vss=0V)

ltem	Symbol	Sta	andard Va		
nem	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd	-0.3	-	+4.0	V
Supply Voltage For LCD Drive	VLCD	-0.3	-	+12.0	V
Input Voltage	Vin	-0.4	-	Vdd+0.3	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Tst	-30	-	+80	°C

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3. ELECTRICAL SPECIFICATIONS (Continued)

3-2. Electrical Characteristics (Vss=0V)

ltem		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage		Vdd - Vss	Ta=0~50°C	2.4	3.0	3.3	V
LCD Drive Voltage (Recommended Voltage)		V _{OP} =Vlcd-Vss	Ta=25°C	8.7	9.0	9.3	V
	"H" Level	V IH	Vdd=3.0V65%	0.8Vdd	-	-	V
Input Voltage	"L" Level	V _{IL}	VDD=3.0VO3%	-	-	0.2Vdd	V
	"H" Level	V _{oH}	Vdd=3.0V65%	0.8Vdd	-	-	V
Output Voltage	"L" Level	V _{oL}	VDD=3.0VO3%	-	-	0.2Vdd	V
Current Consumption		I _{DD}	VDD=3.0V65% VLCD-VSS =9.0V	-	0.50	1.0	mA

NOTE: 1) Duty Ratio=1/65, Bias Ratio=1/9

2) Measuring in Dots ON-state

3-3. Backlight

3-3-1. Absolute Maximum Ratings at Ta=25 $^\circ\!\mathrm{C}$

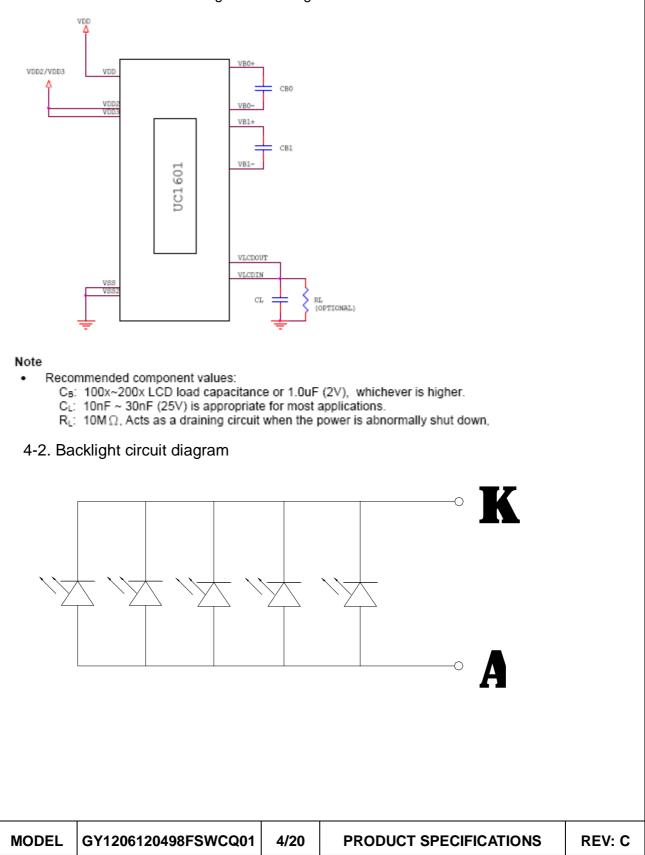
Item	Symbol	Rating	Unit
Peak Forward Current	IFM	112.5	mA
Reverse Voltage	VR	5.0	V
Power Dissipation	Po	382.5	mW
Storage Temperature Range	Tstg	-30~+80	°C
Hand Soldering Temperature	260 ℃	-	

3-3-2. Electronic Optical Characteristics (If=75mA)

	ltem	Symbol	Min.	Тур.	Max	Unit	
Forward	Forward Voltage Luminous Intensity Uniformity AVG. X OF 1931 C.I.E AVG. Y OF 1931 C.I.E		2.8	3.0	3.4	V	
Lumino			1200	1800	2500	cd/m ²	
Uniform			70	-	-	%	
AVG. X			0.26	0.29	0.32	-	
AVG. Y			0.25	0.28	0.31	-	
* The brightness is measured without LCD panel							
ODEL	GY1206120498FSWCQ01	3/20	PRODUCT	SPECIFIC	ATIONS	REV:	

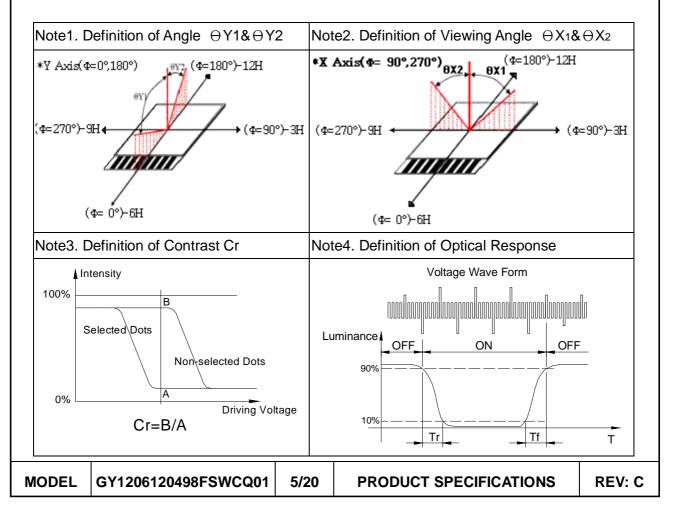
4. BLOCK DIAGRAM

4-1.IC Reference circuit using internal HV generator circuit



5. ELECTRO – OPTICAL CHARACTERISTICS

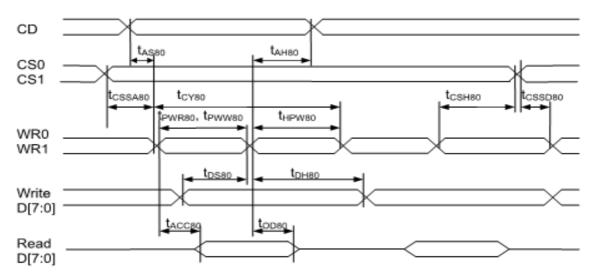
Iter	m	Symbol	Temp.	Min.	Тур.	Max.	Unit	Conditions	Note
	Φ=0°	θ1			28				
Viewing	Φ=180°	⊖2	25 ℃		32		Deg		1 2
Angle Cr <u>></u> 2	Φ=90°	⊖3	230		32		Deg.	-	1,2
	Φ=270°	θ4			33				
Viev	Viewing Direction			12 O'clock					
	Contrast Ratio		25 ℃	2.0	5.16	5.88	-	$\Theta = 0^{\circ}$ $\Phi = 0^{\circ}$	3
Respo		Tr	25 °C	-	141	250	ms	$\Theta = 0^{\circ}$	4
Time(rise)		0 °C	-	950	1150	1115	$\Phi = 0^{\circ}$	-
Respo		Tf	25 °C	-	198	250	ms	$\Theta = 0^{\circ}$	4
Time	(fall)	11	0 °C	-	950	1150	1115	$\Phi = 0^{\circ}$	4



Pin NO.	Symbol	1/0	Functions			
1	/CS	Ι	Chip Select or chip address.			
2	/RST	I	When RST="L", all control registers are re-initialized by their default states.			
3	CD	I	Select the incoming command if it is a control instruction or for display data.			
4	WR0		WR[1:0]controls the read/write operation of the host interface. See Host Interface section for details.			
5	WR1	Ι	The meaning of WR[1:0] depends on whether the interface is In the6800 mode, or the 8080 mode. In serial modes, these two pins are not used and can be connected to Vss			
6	D0(SCK)					
7~8	D1~D2		Bi-directional bus for both serial and parallel host interfaces			
9	D3(SDA)	I/O				
10~13	D4~D7					
14	BM0	1	Bus mode:"HL":8080 "HH":6800			
15	BM1	I	BM[1:0] "LH":S9 "LL":S8			
16	VDD	Power	VDD supplies for display data RAM and digital logic.			
17	VSS	Ground	Ground. Connect VSS and VSS2 to the shared GND pin.			
18	VB1+		LCD Bias Voltage. These are the voltage sources to provide SEG driving currents. These voltages are generated			
19	VB1-	Davis	internally. Connect capacitors of CBX value between VBX+ and VBX			
20	VB0-	Power	In COG application, the resistance of these ITO traces directly affects the SEG driving strength of the resulting LCD			
21	VB0+		module. Minimize these trace resistance is critical in achieving high quality image.			
22	VLCD	Power	LCD Power Supply.			
23~24	ВС	Power	Backlight Cathode (K-)			
25~26	ВA	Power	Backlight Anode (A+)			

7. AC CHARACTERISTICS

7-1. Parallel Bus Timing Characteristics (for 8080 MCU)



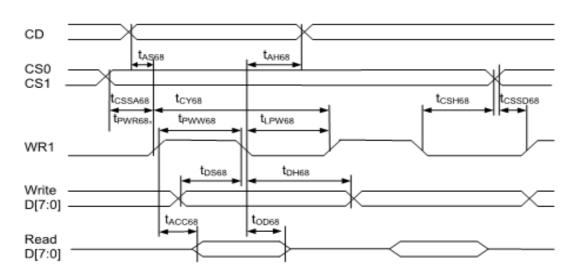
(2.5V ≤ V_{DD} < 3.3V, Ta= -30 to +85°C)

Symbol	Signal	Description	Condition	Min.	Max.	Units
t _{aseo} t _{aheo}	CD	Address setup time Address hold time		0 40	I	nS
t _{CY80}		System cycle time		135	-	nS
t _{PWR80}	WR1	Pulse width (read)		65	-	nS
t _{PWW80}	WR0	Pulse width (write)		65	-	nS
t _{HPW80}	WR0, WR1	High pulse width		65	-	nS
t _{DS80} t _{DH80}	D0~D7	Data setup time Data hold time		30 20	I	nS
t _{acc80} t _{od80}		Read access time Output disable time	C _L = 100pF	_ 10	50 50	nS
tcssaao t _{cssdao} t _{cshao}	CS1/CS0	Chip select setup time		10 10 20		nS

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7. AC CHARACTERISTICS (Continued)

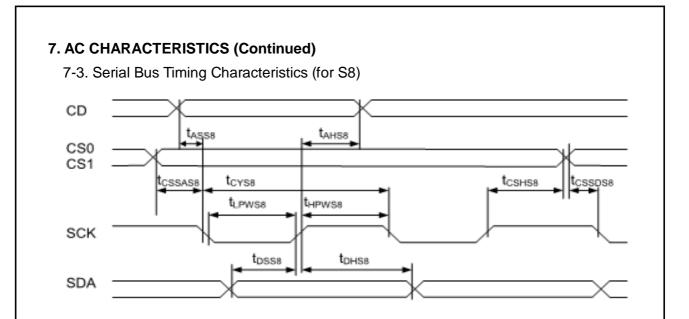
7-2. Parallel Bus Timing Characteristics (for 6800 MCU)



(2.5V ≤ V_{DD} < 3.3V, Ta= -30 to +85°C)

Symbo	Signa	Description	Condition	Min.	Max.	Units
t _{ases} t _{ahes}	CD	Address setup time Address hold time		0 40	-	nS
t _{CY68}		System cycle time		135	-	nS
t _{PWR68}	WR1	Pulse width (read)		65	-	nS
t _{PWW68}		Pulse width (write)		65	-	nS
t _{LPW68}		Low pulse width		65	-	nS
t _{DS68} t _{DH68}	D0~D7	Data setup time Data hold time		30 15	-	nS
t _{ACC68} t _{OD68}		Read access time Output disable time	C _L = 100pF	10	50 50	nS
Tcssa68 Tcssd68 Tcsh68	CS1/CS0	Chip select setup time		10 10 20		nS

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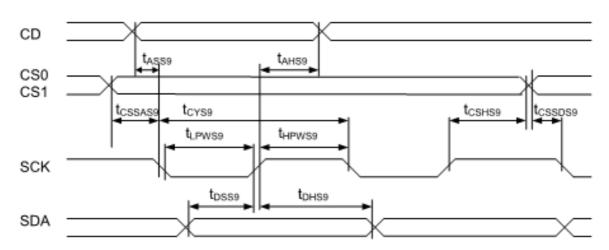
(2.5V ≤ V_{DD} < 3.3V, Ta= -30 to +85[°]C)

Symbol	Signa	Description	Condition	Min.	Max.	Units
t _{ASS8}	CD	Address setup time		0	-	nS
t _{AHS8}	CD	Address hold time		40	-	nS
t _{CYS8}		System cycle time		135	I	nS
t _{LPWS8}	SCK	Low pulse width		65	Ι	nS
t _{HPWS8}		High pulse width		65	Ι	nS
t _{DSS8} t _{DHS8}	SDA	Data setup time Data hold time		30 15	-	nS
tcssase tcssdse tcshse	CS1/CS0	Chip select setup time		10 10 20		nS

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7. AC CHARACTERISTICS (Continued)

7-4. Serial Bus Timing Characteristics (for S9)



(2.5V ≤ V_{DD} < 3.3V, Ta= -30 to +85°C)

Symbol	Signa	Description	Condition	Min.	Max.	Units
t _{ASS9}	CD	Address setup time		0	_	nS
t _{AHS9}	CD	Address hold time		40	-	nS
t _{CYS9}		System cycle time		135	-	nS
t _{LPWS9}	SCK	Low pulse width		65	-	nS
t _{HPWS9}		High pulse width		65	-	nS
t _{DSS9} t _{DHS9}	SDA	Data setup time Data hold time		30 15	Ι	nS
tcssas9 tcssds9 tcshs9	CS1/CS0	Chip select setup time		10 10 20		nS

		[T
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8. INSTRUCTION DESCRIPTION

The following is a list of host commands support by UC1061

0: Control,

W/R:

C/D:

0: Write Cycle,

1: Data 1: Read Cycle

Useful Data bits

-Don't Care

	Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action	Default
1	Write Data Byte	1	0	#	#	#	#	#	#	#	#	Write 1 byte	N/A
2	Read Data Byte	1	1	#	#	#	#	#	#	#	#	Read 1 byte	N/A
3	Get Status	0	1	-	ΜX	MY	RS	WA	DE		-	N/A	
4	Set Column Address LSB	0	0	0	0	0	0	#	#	#	#	Set CA [3:0]	0
	Set Column Address MSB	0	0	0	0	0	1	#	#	#	#	Set CA [7:4]	0
5	Set Multiplexing Rate	0	0	0	0	1	0	0	0	#	#	Set MR [1:0]	11b: 65
6	Set Temp. Compensation	0	0	0	0	1	0	0	1	#	#	Set TC[1:0]	00b: -0.05%/°C
7	Set Panel Loading	0	0	0	0	1	0	1	0	0	#	Set PC[0]	0b: < 15nF
8	Set Pump Control	0	0	0	0	1	0	1	1	#	#	Set PC[2:1]	11b
9	Set Adv. Program Control	0	0	0	0	1	1	0	0	0	R	Set APC[R][7:0],	N/A
	(double byte command)	0	0	#	#	#	#	#	#	#	#	R = 0, or 1	
10	Set Scroll Line	0	0	0	1	#	#	#	#	#	#	Set SL[5:0]	0
11	Set Page Address	0	0	1	0	1	1	#	#	#	#	Set PA[3:0]	0
12	Set V _{BIAS} Potentiometer (double-byte command)	0	0	1 #	0 #	0 #	0 #	0 #	0 #	0 #	1 #	Set PM[7:0]	СОН
13	Set RAM Address Control	0	0	1	0	0	0	1	#	#	#	Set AC[2:0]	001b
14	Set Frame Rate	0	0	1	0	1	0	0	0	0	#	Set LC[3]	Ob
15	Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]	0
16	Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]	0
17	Set Display Enable	0	0	1	0	1	0	1	1	1	#	Set DC[2]	0
18	Set LCD Mapping Control	0	0	1	1	0	0	0	#	#	0	Set LC[2:1]	0
19	System Reset	0	0	1	1	1	0	0	0	1	0	System Reset	N/A
20	NOP	0	0	1	1	1	0	0	0	1	1	No operation	N/A
21	Set Test Control	0	0	1	1	1	0	0	1	T	Т	For testing only.	N/A
	(double byte command)	0	0	#	#	#	#	#	#	#	#	Do not use.	
22	Set LCD Bias Ratio	0	0	1	1	1	0	1	0	#	#	Set BR[1:0]	11b: 9
23	Reset Cursor Update Mode	0	0	1	1	1	0	1	1	1	0	AC[3]=0, CA=CR	N/A
24	Set Cursor Update Mode	0	0	1	1	1	0	1	1	1	1	AC[3]=1, CR=CA	N/A

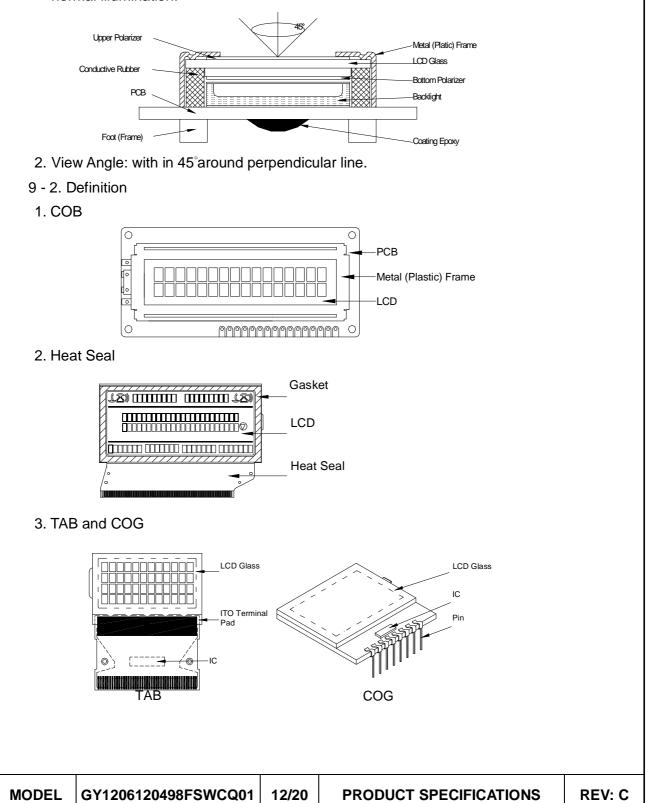
* Other than commands listed above, all other bit patterns result in NOP (No operation).

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9. QUALITY SPECIFICATIONS

- 9 1. LCM Appearance and Electric inspection Condition
 - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



9. QUALITY SPECIFICATIONS (Continued)

9-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (\parallel) ordinary single inspection is used.

2.Acceptance

Major defect:	AQL = 0.25
Minor defect:	AQL = 0.65

9-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards			
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject		
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject		
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject		
Major	PCB cutting defect	Exceed the dimension of drawing	Reject		

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not read	able	Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing wrong component or wrong orienta		Reject
Minor	Component position shift component soldering p X D D Z Z Z		Reject Reject
Minor	Component tilt compone D soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component	AD θ≤20° PCB	Reject
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9. QUALITY SECIFICATIONS (Continued)

9-4. Criteria (Continued)

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards					
Major	Crack / breakage	Anywhere	Reject				
		W	L	Acceptable of Scratch			
		w<0.03mm	Any	Ignore			
		0.03mm <u><</u> w<0.05mm	L <u><</u> 5.0mm	2			
Minor	Frame Scratch	0.05mm <u><</u> w<0.1mm	L <u><</u> 3.0mm	1			
-		w <u>></u> 0.1mm	Any	0			
		Note: 1. Above criteria distance greater than 2. Scratch on th visible) can be ignored					
				Acceptable of Dents / Pricks			
		⊕ <u><</u> 1.0mr	2				
	Frame Dent, Prick	1.0<⊕ <u><</u> 1.5ı	mm	1			
Minor	$\Phi = \frac{L + W}{M}$	1.5mm>0	Þ	0			
Minor $\Phi = \frac{L + W}{2}$	Note: 1. Above criteria applicable to any two der pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (visible) can be ignored						
Minor	Frame Deformation	Exceed the	dimension of a	drawing			
Minor	Metal Frame Oxidation		Any rust				

4. Flexible Film Connector (FFC)

Tilte	ط مماطم سأسم م		
1110	d soldering	Within the angle <u>+</u> 3°	Acceptable
Uneven se	older joint /bump		Reject
	Φ_{-} L+W	Expose the conductive line	Reject
$\psi = \frac{1}{2}$	Φ > 1.0mm	Reject	
Y-*	→Z _K ↓	Y > 1/3D	Reject
	X > 1/2Z	Reject	
	Hole Position s	Hole $\Psi = \frac{2}{2}$ Position shift $\Psi = \frac{2}{2}$	Hole $\Phi = \frac{L + W}{2}$ Expose the conductive line Position shift $Y > \frac{V}{R} = \frac{D}{R}$ $Y > 1/3D$

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9. QUALITY SPECIFICATIONS (Continued)

9-4. Criteria (Continued)

5. Screw

Defect	Inspection Item Inspection Standard		S	
Major	Screw missing/loosen		Reject	
Minor	Screw oxidation	Any rust	Reject	
Minor	Screw deformation	Difficult to accept screw driver	Reject	

6. Heat seal TCP FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Φ > 0.2mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
		⊕ <u><</u> 0.10mm	Ignore			
	0.10<⊕ <u><</u> 0.15mm	2				
Minor		0.15<⊕ <u><</u> 0.2mm	1			
		⊕>0.2mm	0			
		The distance between any two spots should be \geq Any spot/dot/void outside of viewing area is accept				
Minor	Protective film tilt	Not fully cover LCD	Reject			
Major	COG coating	Not fully cover ITO circuit	Reject			

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

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9. QUALITY SPECIFICATIONS (Continued)

9-4. Criteria (Continued)

9. Inspection Specification of LCD

Defect	Insp	pect Item		I	nsp	ection	St	andard	S	
		* Glass Scratch	W	١	<i>N</i> <u><</u> 0.0		0.0	3 <w<u><0.05</w<u>	5 V	V>0.05
		* Polarizer Scratch	L		L<5			L<3		Any
Minor	I INPAR LIPTECT	 Fiber and Linear 	ACC. NO.	1			1		Reject	
		material	Note	L is the	leng	th and W	is the	width of	the de	fect
		* Foreign material	Φ	Φ <u><</u> ().1	0.1< ⊕ <u><</u>	0.15	0.15< Φ	<u><</u> 0.2	Ф >0.2
	Black Spot and	between glass and polarizer or glass	ACC. NO.	3EA /	1PC	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note					of the de cts > 10m		
		* Unobvious	Φ	⊕ <u><</u> 0	.1	0.1<⊕ <u><</u>	0.15	0.15<⊕	<u><</u> 0.2	⊕>0.2
	White Spot	transparant foreign material between	ACC. NO.	3EA / 1	IPC	2		1		0
Minor and	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note			-		of the de cts > 10m		
	Segment Defect		Φ	Φ <u><</u> 0.1	10	0.10<⊕ <u><</u> 0.20		⊕>0.2		
		egment	ACC. NO.	3EA /1	⊃C	2			0	
Minor				W is m	ore th	an 1/2 s	egmer	nt width	F	Reject
			Note	$\Phi = -$ Distanc	_	-	o defe	ct is 10m	m	
			Φ	⊕ <u><</u> 0	.10	0	. 10 <⊄	≥ <u><</u> 0.20		Ф>0.2
Minor	Protuberant Segment					/2 Seg , W <u><</u> 0.2			Ignore	
	Segment	Φ = (L + W) / 2	ACC. NO.	3EA /	1PC		2			0
			1. Seg	gment						
			E	3	B <u><</u> 0.	4mm ().4 <b< td=""><td><u><</u>1.0mm</td><td>B>´</td><td>l.0mm</td></b<>	<u><</u> 1.0mm	B>´	l.0mm
			B-	A	B-A<	:1/2B	B-A	<0.2	B-A	<0.25
Minor	Assembly Mis-alignment		Juc	dge Acceptable A		Acce	Acceptable Acceptable			
		· · · · · · · · · · · · · · · · · · ·	2. Dot	Matrix						
				ormatior						Reject
Minor Stain on LCD Panel Surface Accept when stains can be wiped lightly with a soft clot or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"						Otherwis	se, ju	dged acc		
DEL	GY120612049	8FSWCQ01 16/2	_					ATIONS		REV:

10. RELIABILITY

NO.	ltem	Condition	Criterion
1	High Temperature Operating	70℃, 96Hrs	
2	Low Temperature Operating	-20℃, 96Hrs	
3	High Humidity	60℃, 90%RH, 96Hrs	
4	High Temperature Storage	80℃, 96Hrs	No defect in cosmetic
5	Low Temperature Storage	-30℃, 96Hrs	and operational function allowable.
6	Vibration	Random wave 10 ~ 100Hz Acceleration: 2G 60 Minute	Total current Consumption should be below double of initial value.
7	Thermal Shock	-10℃ to 25℃ to 60℃ (60Min) (15Min) (60Min) 10Cycles	
8	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and -1 ~ -5kV	There will be discharged ten times at every discharging
ð	LOD rearing	Air Discharge Voltage: +1 ~ 8kV and -1 ~ -8kV	voltage gap is 1kV.

Note: 1) Above conditions are suitable for GOLDENTEK standard products.

2) For restrict products, the test conditions listed as above must be revised.

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11. HANDLING PRECAUTIONS

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichlorotrifloroethane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or Vss, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.

- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
 - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.

MODEL GY1206120498FSWCQ01 18/20 PRODUCT SPECIFICATIONS REV: 0

11. HANDLING PRECAUTIONS (Continued)

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.

However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

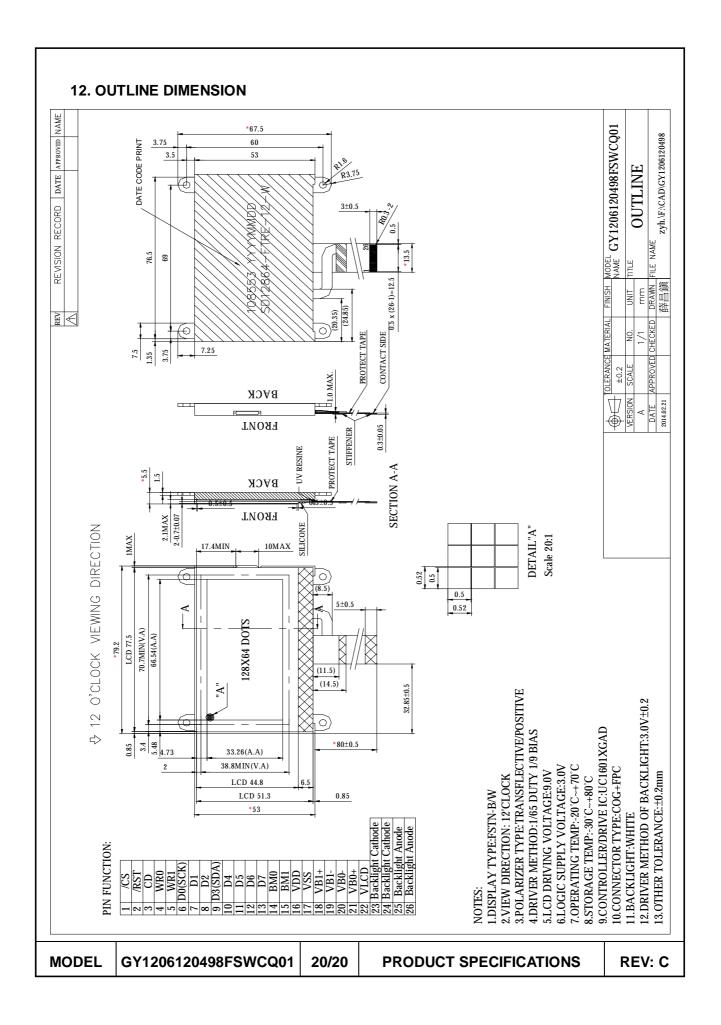
Usage under the relative condition of 40°C, 80%RH or less is required.

(6) Storage

In the case of storing for a long period of time (for instance ,for years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.
 Which should be burned up later.
 - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

MODEL	GY1206120498FSWCQ01	19/20	PRODUCT SPECIFICATIONS	REV: C



SAMPLE OUTGOING INSPECTION REPORT (LCM)

Data: 2014/02/24

NO.: QAD08007

Cu	stomer	Product NO.			Driving Voltage			Testing Condition			Quantity				
Swissdis AG		GY12061	20498F	SWCO	Q01	Vo	VOP=9.0V			25 ℃			10 Pcs		
Inspection Result															
lt	ems	Specification													
Displ	ay Mode	W / B Mode O B / W Mode O Yellow Mode O Blue Mode O Gray Mode													
Polarizer Type		(Transflective					○ Transmissive						
Viewing direction		03) 6 O'a	6 O'clock				9 O'clock • 12 O'clock							
					Ele	ctrical	/ Ap	pea	ranc	е					
ltem		Inspection Method					Specification					Inspection Result			
Appearance		Spot Gauge Caliper				Fi	Final Inspection Criteria					• OI	ĸ	⊖ NG	
Electrical		LCM Tester					Product Specification					• OI	ĸ	⊖ NG	
Pattern		LCM Tester					Drawing					• OI	ĸ	⊖ NG	
Dimension / Supply Current															
ltem	Spec.(m	ec.(mm) NO.1 NO.2 NO.3 NO.4 NO.5 Result					Fig.								
L1	79.2 <u>+</u> 0.	2 79.12	79.13	79.09	79.10	79.08	•	OK	\bigcirc N	IG					
L2	13.5 <u>+</u> 0.	2 13.46	13.48	13.47	13.48	13.53	•	OK	\bigcirc N	IG					
W1	67.5 <u>+</u> 0.	2 67.33	67.36	67.35	67.38	67.40		OK	\bigcirc N	IG		I 128X64 DOTS I NOUL			
W2	80 <u>+</u> 0.5	5 79.98	79.90	79.80	79.93	79.86		OK	() N	IG					
Т	5.5 <u>+</u> 0.2	2 5.47	5.47	5.47	5.48	5.49		ОК	0 N	IG					
IDD	2.0mA(m	ax) 0.80	0.80	0.80	0.80	0.80	•	OK	() N	IG	1	L2	4	I	
Designed		Joan			Checked		/			·	Appr	oved	Wallace		
Doc. NO.: F10018A															

Attached File: Initial code

ComWrite(0x26);	//Set temp. compensation							
ComWrite(0xc4);	// Set LCD mapping control							
ComWrite(0x0eb);	// Set LCD bias							
ComWrite(0x88);	// set RAM address control							
ComWrite(0x81);	// Set gain and potentiometer (Double Byte Command)							
ComWrite(0x65);	// Set reference voltage register							
ComWrite(0x2f);	// Set Pump Control: internal VLCD							